

### SEMITOP® 2 Press-Fit

#### SiC MOSFET Module

### **Engineering Sample** SK25MH120SCTp

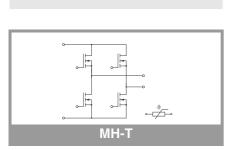
**Target Data** 

#### **Features**

- 1200V SiC Planar MOSFET
- Single phase inverter topology
- One screw mounting module
- Fully compatible with other SEMITOP® Press-Fit types
- Improved thermal performance by aluminum oxide substrate
- Ultra Low inductance design
- · Extremely fast switching
- UL recognized, file no. E63532

#### Typical Applications\*

- · Solar inverter
- UPS
- · Power Supply



Absolute	Maximum Rati	ngs		
Symbol	Conditions		Values	Unit
MOSFET	1			•
$V_{DSS}$			1200	V
I <sub>D</sub>	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 25 °C	26	Α
		T <sub>s</sub> = 70 °C	21	Α
I <sub>DM</sub>	PW≤10μs, duty cycle≤1%		140	Α
I <sub>DRM</sub>			42	Α
V <sub>GS</sub>			-6 22	V
Tj			-40 175	°C
Integrated	d body diode			
I <sub>FM</sub>	PW≤10μs, duty cycle≤1%		140	Α
I <sub>FRM</sub>			42	Α

Absolute Maximum Ratings					
Symbol	Conditions	Values			
Module					
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 100 °C, T <sub>S</sub> = 60°C, per pin	40	Α		
T <sub>stg</sub>		-40 125	°C		
V <sub>isol</sub>	AC, sinusoidal, t = 1 min	2500	V		

Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
MOSFET	1		•			
$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_j = 25 \text{ °C}$		1200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 4.4$ mA, $T_j = 25$ °C		1.6		4	V
I <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 1200 \text{ V}, T_j = 25 ^{\circ}\text{C}$				1	mA
I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = 22 \text{ V}, T_j = 25 ^{\circ}\text{C}$				100	nA
R <sub>DS(on)</sub>	V <sub>GS</sub> = 18 V	T <sub>j</sub> = 25 °C		80	111	mΩ
	I <sub>D</sub> = 10 A chiplevel	T <sub>j</sub> = 150 °C		124		mΩ
C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 800 V, f = 1 MHz			2070		pF
C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 80$	0 V, f = 1 MHz		80		pF
C <sub>rss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 80$	0 V, f = 1 MHz		20		pF
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			9.0		Ω
$Q_{G}$	V <sub>DS</sub> =400V, V <sub>GS</sub> =18	V, I <sub>D</sub> = 10 A		110		nC
t <sub>d(on)</sub>	$V_{DD} = 600 \text{ V}$ $V_{GS} = 20/-5 \text{ V}$	T <sub>j</sub> = 150 °C				ns
t <sub>d(off)</sub>		T <sub>j</sub> = 150 °C				ns
t <sub>r</sub>	I <sub>D</sub> = 25 A	T <sub>j</sub> = 150 °C				ns
t <sub>f</sub>	di/dt <sub>off</sub> = 2.2 kA/μs	T <sub>j</sub> = 150 °C				ns
E <sub>on</sub>		T <sub>j</sub> = 150 °C		0.5		mJ
E <sub>off</sub>		T <sub>j</sub> = 150 °C		0.2		mJ
R <sub>th(j-s)</sub>	per MOSFET		1.4			K/W
Integrated	d body diode					
$V_F = V_{SD}$	$-I_D = 20 \text{ A}$	T <sub>j</sub> = 25 °C		5.75		V
	V <sub>GS</sub> = 0 V chiplevel	T <sub>j</sub> = 150 °C		5.20		V
$V_{F0} = V_{SD0}$	ahinlaval	T <sub>j</sub> = 25 °C		1.35		V
	chiplevel	T <sub>j</sub> = 150 °C		1.00		V
$r_F = r_{SD}$	chiployol	T <sub>j</sub> = 25 °C		220		mΩ
	chiplevel	T <sub>j</sub> = 150 °C		210		mΩ
t <sub>rr</sub>	V <sub>DD</sub> = 600 V -I <sub>D</sub> = 25 A			-		ns
Q <sub>rr</sub>				-		μC
I <sub>rr</sub>	1,, -,,			-		Α
E <sub>rr</sub>	$V_{GS} = -5 V$			0.17		mJ



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**Target Data** 

#### **Features**

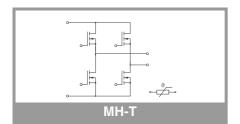
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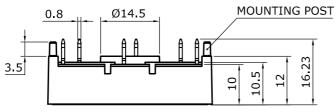
Characteristics						
Symbol	Conditions	min.	typ.	max.	Unit	
Module						
L <sub>CE</sub>			t.b.d.		nΗ	
Ms	to heatsink	1.8		2	Nm	
W	weight		19		g	

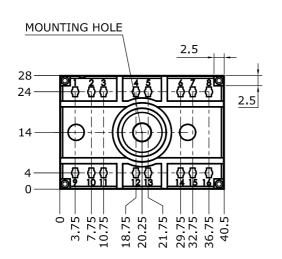
Characteristics						
Symbol	Conditions	min.	typ.	max.	Unit	
Temperature Sensor						
R <sub>100</sub>	T <sub>r</sub> = 100 °C	493 ± 5%		Ω		
B <sub>100/125</sub>	$R_{(T)} = R_{100} exp[B_{100/125}(1/T-1/T_{100})]; T[K];$	3550 ±2%		К		

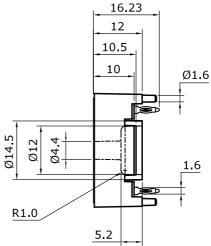


Dimensions: mm

Tolerance system: ISO 2768-m







Suggested drilled hole diameter for terminal pins in the circuit board:

minimum: 1.575 mmtypical: 1.6 mm

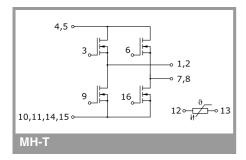
• maximum: 1.625 mm

Suggested hole diameter for the mounting post in the circuit board:

• 2 mm

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SEMITOP 2 Press-Fit



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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